



SOD123F

plastic surface-mounted package; 2 leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SOD123F
Package type industry code	SOD123F
Package style descriptive code	SOD (small outline diode)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-3-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.5	-	2.6	2.7	mm
E	package width	1.5	-	1.6	1.7	mm
A	seated height	1	-	1.1	1.2	mm
n ₂	actual quantity of termination	-	-	2	-	



2. Package outline

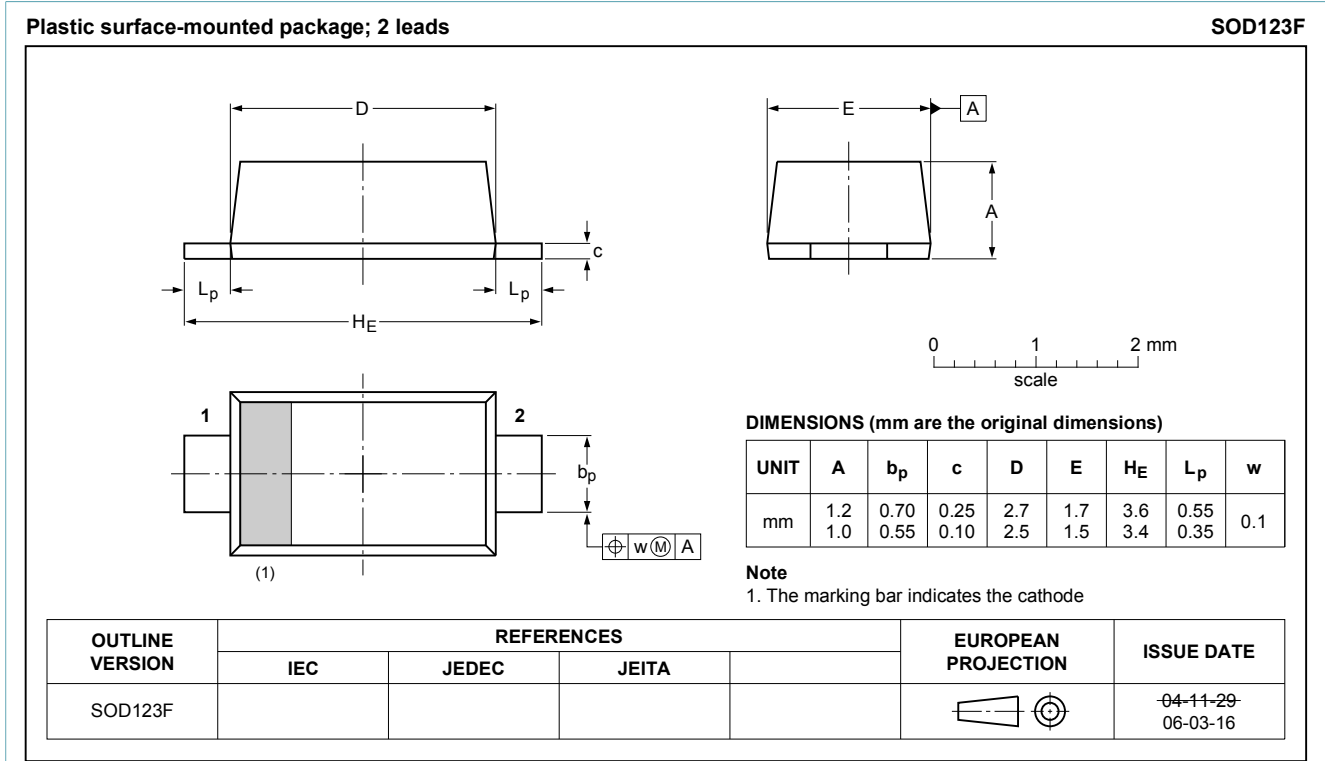


Fig. 1. Package outline SOD123F

3. Soldering

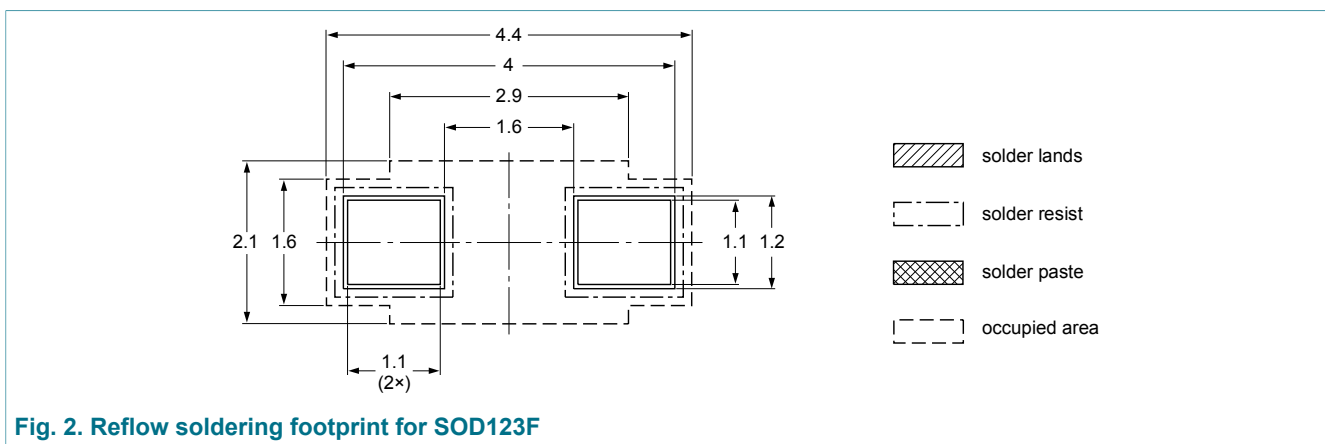


Fig. 2. Reflow soldering footprint for SOD123F

4. Legal information

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